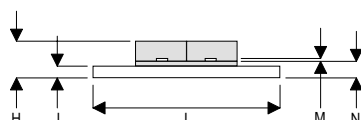
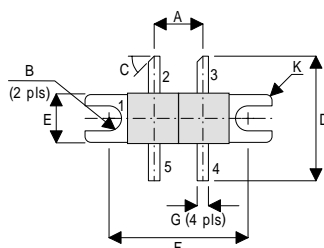


## MECHANICAL DATA



DK

PIN 1 SOURCE (COMMON) PIN 2 DRAIN 1  
PIN 3 DRAIN 2 PIN 4 GATE 2  
PIN 5 GATE 1

| DIM | mm    | Tol. | Inches | Tol.  |
|-----|-------|------|--------|-------|
| A   | 6.45  | 0.13 | 0.254  | 0.005 |
| B   | 1.65R | 0.13 | 0.065R | 0.005 |
| C   | 45°   | 5°   | 45°    | 5°    |
| D   | 16.51 | 0.76 | 0.650  | 0.03  |
| E   | 6.47  | 0.13 | 0.255  | 0.005 |
| F   | 18.41 | 0.13 | 0.725  | 0.005 |
| G   | 1.52  | 0.13 | 0.060  | 0.005 |
| H   | 4.82  | 0.25 | 0.190  | 0.010 |
| I   | 24.76 | 0.13 | 0.975  | 0.005 |
| J   | 1.52  | 0.13 | 0.060  | 0.005 |
| K   | 0.81R | 0.13 | 0.032R | 0.005 |
| M   | 0.13  | 0.02 | 0.005  | 0.001 |
| N   | 2.16  | 0.13 | 0.085  | 0.005 |

# GOLD METALLISED MULTI-PURPOSE SILICON DMOS RF FET 60W – 12.5V – 500MHz PUSH-PULL

## FEATURES

- SIMPLIFIED AMPLIFIER DESIGN
- SUITABLE FOR BROAD BAND APPLICATIONS
- LOW  $C_{rss}$
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN – 10 dB MINIMUM

## APPLICATIONS

- HF/VHF/UHF COMMUNICATIONS  
from 1 MHz to 500 MHz

ABSOLUTE MAXIMUM RATINGS ( $T_{case} = 25^{\circ}C$  unless otherwise stated)

|              |  |              |
|--------------|--|--------------|
| $P_D$        | Power Dissipation                      | 290W         |
| $BV_{DSS}$   | Drain – Source Breakdown Voltage *     | 40V          |
| $BV_{GSS}$   | Gate – Source Breakdown Voltage *      | $\pm 20V$    |
| $I_{D(sat)}$ | Drain Current*                         | 30A          |
| $T_{stg}$    | Storage Temperature                    | -65 to 150°C |
| $T_j$        | Maximum Operating Junction Temperature | 200°C        |

\* Per Side

Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.

## ELECTRICAL CHARACTERISTICS (T<sub>case</sub> = 25°C unless otherwise stated)

| Parameter   | Test Conditions   | Min. | Typ. | Max. | Unit |
|---|---|------|------|------|------|
| <b>PER SIDE</b>                                   |   |      |      |      |      |
| B <sub>V</sub> DSS Drain–Source Breakdown Voltage | V <sub>GS</sub> = 0 I <sub>D</sub> = 100mA              | 40   |      |      | V    |
| I <sub>D</sub> SS Zero Gate Voltage Drain Current | V <sub>DS</sub> = 12.5V V <sub>GS</sub> = 0             |      |      | 1    | mA   |
| I <sub>G</sub> SS Gate Leakage Current            | V <sub>GS</sub> = 20V V <sub>DS</sub> = 0               |      |      | 1    | μA   |
| V <sub>GS(th)</sub> Gate Threshold Voltage*       | I <sub>D</sub> = 10mA V <sub>DS</sub> = V <sub>GS</sub> | 1    |      | 7    | V    |
| g <sub>fs</sub> Forward Transconductance*         | V <sub>DS</sub> = 10V I <sub>D</sub> = 3A               | 2.4  |      |      | mhos |
| <b>TOTAL DEVICE</b>                               |   |      |      |      |      |
| G <sub>PS</sub> Common Source Power Gain          | P <sub>O</sub> = 60W                                    | 10   |      |      | dB   |
| η Drain Efficiency                                | V <sub>DS</sub> = 12.5V I <sub>DQ</sub> = 2.4A          | 50   |      |      | %    |
| VSWR Load Mismatch Tolerance                      | f = 500MHz  | 20:1 |      |      | —    |
| <b>PER SIDE</b>                                   |   |      |      |      |      |
| C <sub>iss</sub> Input Capacitance                | V <sub>DS</sub> = 0V V <sub>GS</sub> = –5V f = 1MHz     |      |      | 180  | pF   |
| C <sub>oss</sub> Output Capacitance               | V <sub>DS</sub> = 12.5V V <sub>GS</sub> = 0 f = 1MHz    |      |      | 120  | pF   |
| C <sub>rss</sub> Reverse Transfer Capacitance     | V <sub>DS</sub> = 12.5V V <sub>GS</sub> = 0 f = 1MHz    |      |      | 12   | pF   |

\* Pulse Test: Pulse Duration = 300 μs , Duty Cycle ≤ 2%

## HAZARDOUS MATERIAL WARNING

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area.

**THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.**

## THERMAL DATA

|                       |                                    |                |
|-----------------------|------------------------------------|----------------|
| R <sub>THj-case</sub> | Thermal Resistance Junction – Case | Max. 0.6°C / W |
|-----------------------|------------------------------------|----------------|

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